

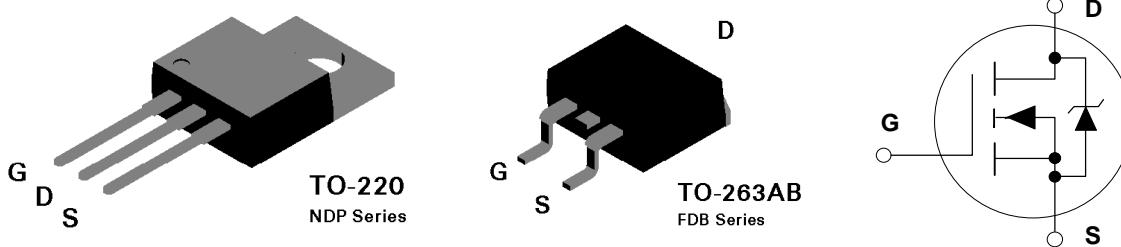
NDP510A / NDP510AE / NDP510B / NDP510BE NDB510A / NDB510AE / NDB510B / NDB510BE N-Channel Enhancement Mode Field Effect Transistor

General Description

These N-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- 15 and 13A, 100V. $R_{DS(ON)} = 0.12$ and 0.15Ω .
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design (3 million/in^2) for extremely low $R_{DS(ON)}$.
- TO-220 and TO-263 (D²PAK) package for both through hole and surface mount applications.



Absolute Maximum Ratings

$T_c = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | NDP510A NDB510A | NDP510AE NDB510AE | NDP510B NDB510B | NDP510BE NDB510BE | Units |
|----------------|---|--------------------|----------------------|--------------------|----------------------|---------------------|
| V_{DSS} | Drain-Source Voltage | | 100 | | | V |
| V_{DGR} | Drain-Gate Voltage ($R_{GS} \leq 1 \text{ M}\Omega$) | | 100 | | | V |
| V_{GSS} | Gate-Source Voltage - Continuous | | ± 20 | | | V |
| | - Nonrepetitive ($t_p < 50 \mu\text{s}$) | | ± 40 | | | V |
| I_D | Drain Current - Continuous | 15 | | 13 | | A |
| | - Pulsed | 60 | | 52 | | A |
| P_D | Total Power Dissipation @ $T_c = 25^\circ\text{C}$ | | 75 | | | W |
| | Derate above 25°C | | 0.5 | | | W/ $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | | -65 to 175 | | | $^\circ\text{C}$ |
| T_L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 275 | | | $^\circ\text{C}$ |

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Type | Min | Typ | Max | Units |
|--|--|---|--|--|-------|------|---------------|
| DRAIN-SOURCE AVALANCHE RATINGS (Note 1) | | | | | | | |
| E_{AS} | Single Pulse Drain-Source Avalanche Energy | $V_{DD} = 25 \text{ V}$, $I_D = 15 \text{ A}$ | NDP510AE NDP510BE NDB510AE NDB510BE | | | 65 | mJ |
| I_{AR} | Maximum Drain-Source Avalanche Current | | | | | 15 | A |
| OFF CHARACTERISTICS | | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | ALL | 100 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$ $T_J = 125^\circ\text{C}$ | ALL | | | 250 | μA |
| | | | | | | 1 | mA |
| I_{GSSF} | Gate - Body Leakage, Forward | $V_{GS} = 20 \text{ V}$, $V_{DS} = 0 \text{ V}$ | ALL | | | 100 | nA |
| I_{GSSR} | Gate - Body Leakage, Reverse | $V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$ | ALL | | | -100 | nA |
| ON CHARACTERISTICS (Note 2) | | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$ $T_J = 125^\circ\text{C}$ | ALL | 2 | 3 | 4 | V |
| | | | | 1.4 | 2.3 | 3.6 | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10 \text{ V}$, $I_D = 7.5 \text{ A}$ $T_J = 125^\circ\text{C}$ | NDP510A NDP510AE NDB510A NDB510AE | | 0.088 | 0.12 | Ω |
| | | | | | 0.16 | 0.24 | Ω |
| | | $V_{GS} = 10 \text{ V}$, $I_D = 6.5 \text{ A}$ $T_J = 125^\circ\text{C}$ | NDP510B NDP510BE NDB510B NDB510BE | | | 0.15 | Ω |
| | | | | | | 0.3 | Ω |
| $I_{D(on)}$ | On-State Drain Current | $V_{GS} = 10 \text{ V}$, $V_{DS} = 10 \text{ V}$ | NDP510A NDP510AE NDB510A NDB510AE | 15 | | | A |
| | | | | NDP510B NDP510BE NDB510B NDB510BE | 13 | | A |
| g_{FS} | Forward Transconductance | $V_{DS} = 10 \text{ V}$, $I_D = 7.5 \text{ A}$ | ALL | 6 | 8.6 | | S |
| DYNAMIC CHARACTERISTICS | | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS} = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$ | ALL | | 740 | 900 | pF |
| C_{oss} | Output Capacitance | | ALL | | 160 | 180 | pF |
| C_{rss} | Reverse Transfer Capacitance | | ALL | | 40 | 50 | pF |

NDP510.SAM

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Type | Min | Typ | Max | Units |
|---|--|---|--|-----|------|------|-------|
| SWITCHING CHARACTERISTICS (Note 2) | | | | | | | |
| $t_{D(ON)}$ | Turn - On Delay Time | $V_{DD} = 50 \text{ V}, I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}, R_{GEN} = 24 \Omega$ | ALL | | 10 | 20 | nS |
| t_r | Turn - On Rise Time | | ALL | | 63 | 100 | nS |
| $t_{D(OFF)}$ | Turn - Off Delay Time | | ALL | | 49 | 80 | nS |
| t_f | Turn - Off Fall Time | | ALL | | 45 | 75 | nS |
| Q_g | Total Gate Charge | $V_{DS} = 80 \text{ V}, I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}$ | ALL | | 22.5 | 30 | nC |
| Q_{gs} | Gate-Source Charge | | ALL | | 4.5 | | nC |
| Q_{gd} | Gate-Drain Charge | | ALL | | 10.5 | | nC |
| DRAIN-SOURCE DIODE CHARACTERISTICS | | | | | | | |
| I_s | Maximum Continuos Drain-Source Diode Forward Current | $V_{GS} = 0 \text{ V}, I_s = 7.5 \text{ A}$ | NDP510A NDP510AE NDB510A NDB510AE | | | 15 | A |
| | | | NDP510B NDP510BE NDB510B NDB510BE | | | 13 | A |
| I_{SM} | Maximum Pulsed Drain-Source Diode Forward Current | $T_J = 125^\circ\text{C}$ | NDP510A NDP510AE NDB510A NDB510AE | | | 60 | A |
| | | | NDP510B NDP510BE NDB510B NDB510BE | | | 52 | A |
| V_{SD} (Note 2) | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_s = 15 \text{ A}$ | ALL | | 0.89 | 1.3 | V |
| | | | | | 0.85 | 1.2 | V |
| t_{rr} | Reverse Recovery Time | $V_{GS} = 0 \text{ V}, I_s = 15 \text{ A}, dI_s/dt = 100 \text{ A}/\mu\text{s}$ | ALL | | 98 | 140 | ns |
| I_{rr} | Reverse Recovery Current | | ALL | | 6.8 | 10 | A |
| THERMAL CHARACTERISTICS | | | | | | | |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | | ALL | | | 2 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | ALL | | | 62.5 | °C/W |

Notes:

1. NDP510A/510B and NDB510A/510B are not rated for operation in avalanche mode.
2. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

Typical Electrical Characteristics

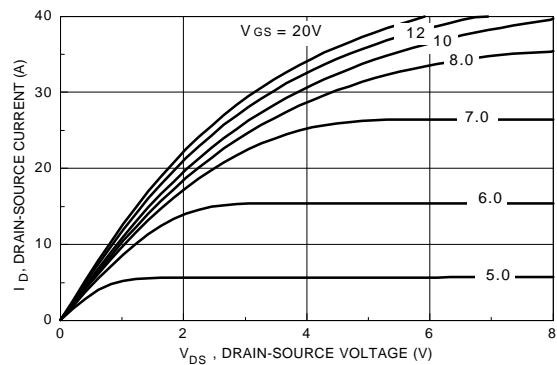


Figure 1. On-Region Characteristics.

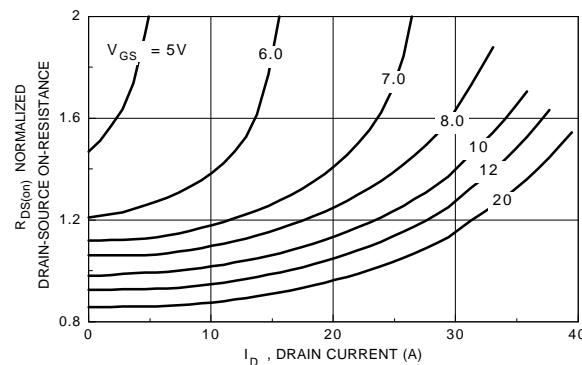


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

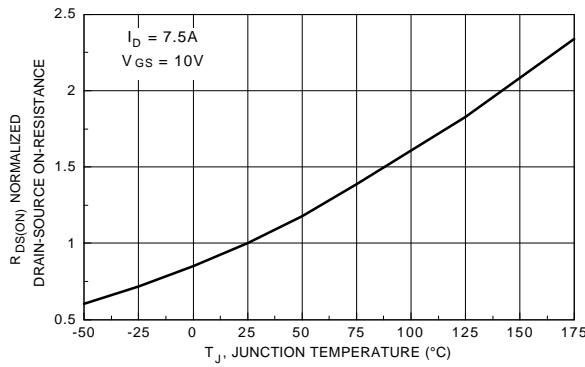


Figure 3. On-Resistance Variation with Temperature.

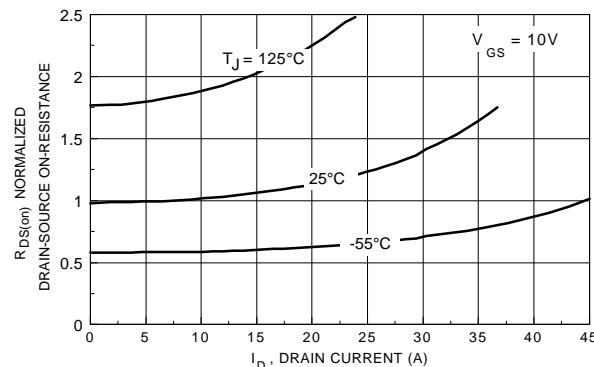


Figure 4. On-Resistance Variation with Drain Current and Temperature.

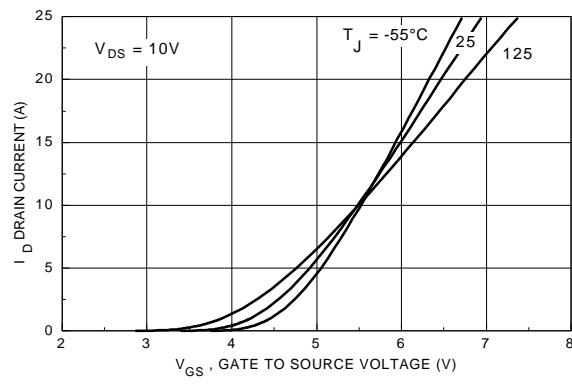


Figure 5. Transfer Characteristics.

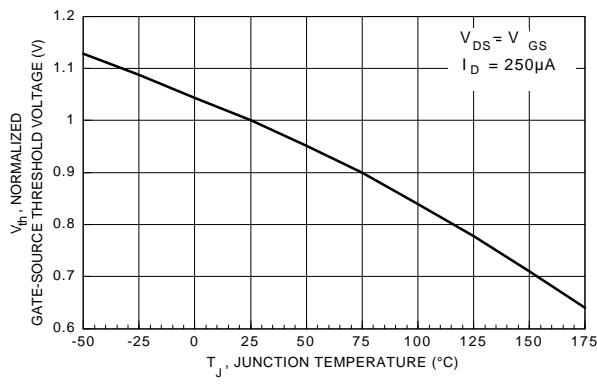


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

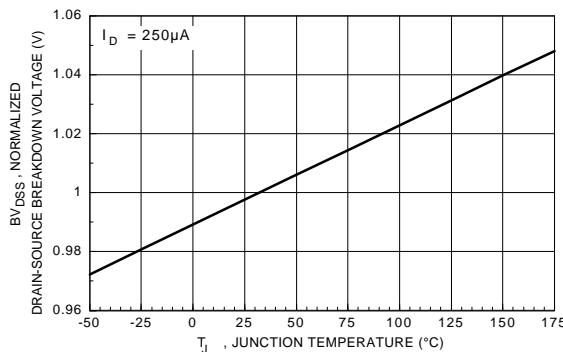


Figure 7. Breakdown Voltage Variation with Temperature.

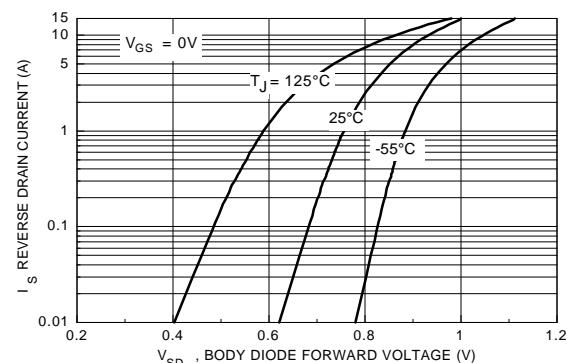


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

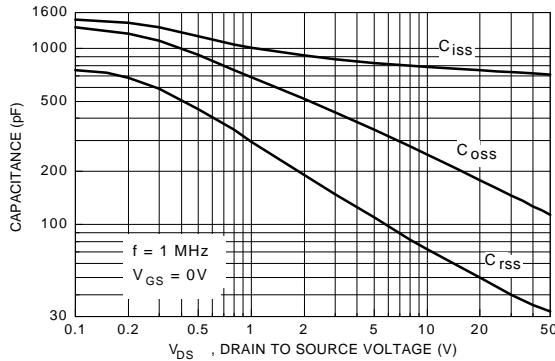


Figure 9. Capacitance Characteristics.

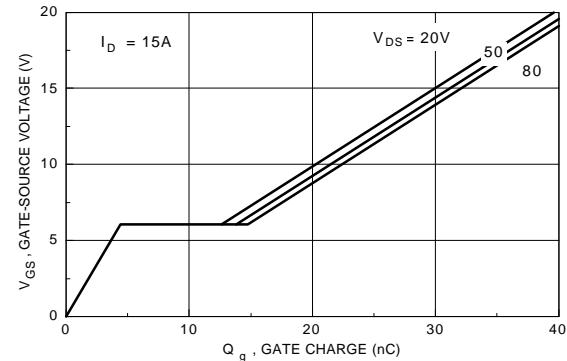


Figure 10. Gate Charge Characteristics.

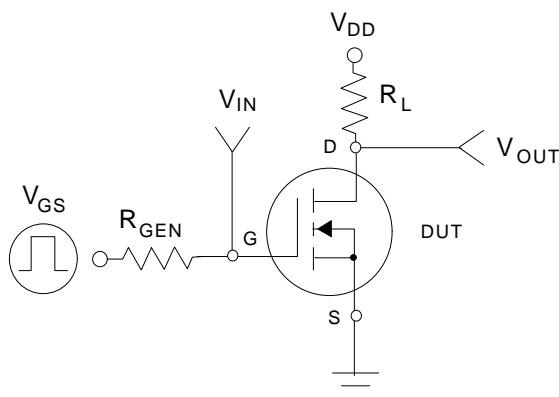


Figure 11. Switching Test Circuit.

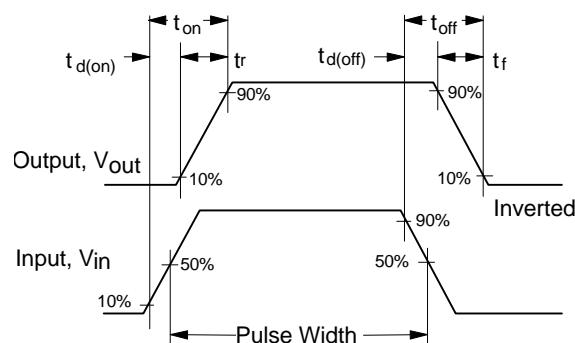


Figure 12. Switching Waveforms.

Typical Electrical Characteristics (continued)

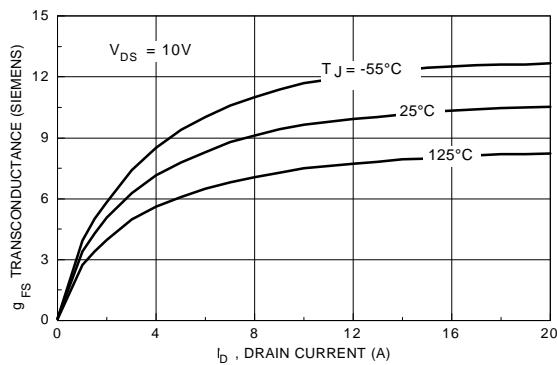


Figure 13. Transconductance Variation with Drain Current and Temperature.

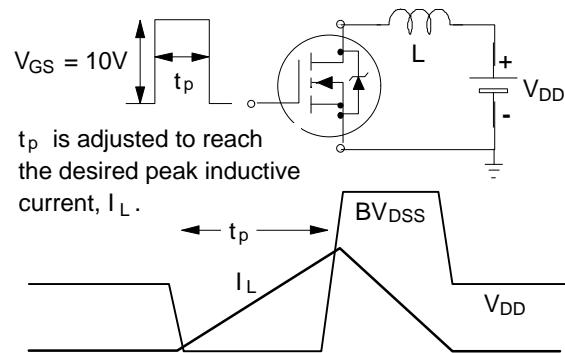


Figure 14. Unclamped Inductive Load Circuit and Waveforms.

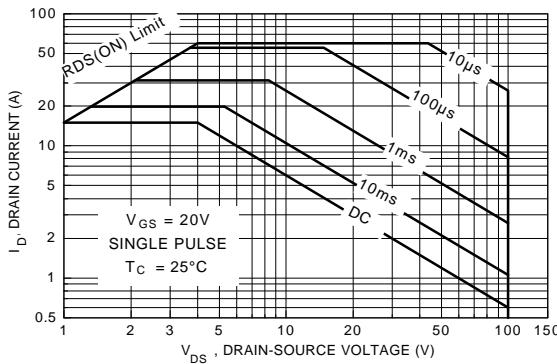


Figure 15. Maximum Safe Operating Area.

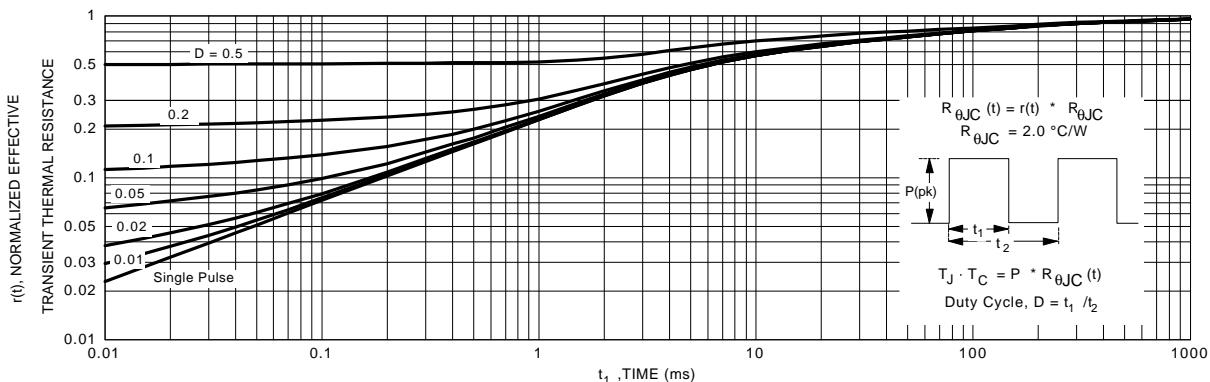


Figure 16. Transient Thermal Response Curve.